

### **LISTING OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

**Claim 1 (previously presented):** A wafer holder for semiconductor manufacturing equipment, the wafer holder having a surface for carrying wafers of a predetermined diameter and comprising:

a high-frequency RF power-generating electrode circuit round in form, built into the wafer holder, the electrode circuit diameter being greater than said predetermined diameter of the wafers that the wafer holder carries; wherein

the distance between the periphery of the high-frequency RF power-generating electrode circuit built into the wafer holder and the periphery of the wafer holder is longer than the distance separating said electrode circuit from the wafer-carrying surface.

**Claims 2 and 3 (canceled)**

**Claim 4 (previously presented):** Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 1 is installed.

**Claim 5 (canceled)**